Din-Tek SEMICONDUCTOR

DTB6401

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P-Channel 60-V (D-S) MOSFET

PRODUCT SUMMARY			
V_{DS} (V)	$R_{DS(on)}$ (Ω)	I_D (A)[a]	Q_g (Typ.)
-60	0.078 at V_{GS} = -10 V	-4.0	2.1 nC
	0.089 at V_{GS} = -4.5 V	-3.1	

FEATURES

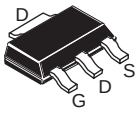
- TrenchFET II Power MOSFET
- 100 % R_g Tested
- 100 % UIS Tested

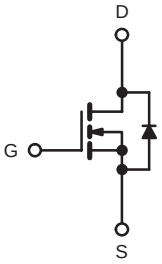
Pb-free
RoHS COMPLIANT

APPLICATIONS

- Battery Switch
- DC/DC Converter

SOT-223





N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS T_A = 25 °C, unless otherwise noted				
Parameter		**Symbol**	**Limit**	**Unit**
Drain-Source Voltage		V_{DS}	-60	V
Gate-Source Voltage		V_{GS}	± 20	
Continuous Drain Current (T_J = 150 °C)	T_C = 25 °C	I_D	-4.0	A
	T_C = 70 °C		-1.8	
	T_A = 25 °C		-2.1[b, c]	
	T_A = 70 °C		-1.5[b, c]	
Pulsed Drain Current		I_{DM}	-16	
Continuous Source-Drain Diode Current	T_C = 25 °C	I_S	-4	
	T_A = 25 °C		-0.91[b, c]	
Avalanche Current	L = 0.1 mH	I_{AS}	-16	
Single-Pulse Avalanche Energy		E_{AS}	1.8	mJ
Maximum Power Dissipation	T_C = 25 °C	P_D	1.66	W
	T_C = 70 °C		1.06	
	T_A = 25 °C		1.09[b, c]	
	T_A = 70 °C		0.7[b, c]	
Operating Junction and Storage Temperature Range		T_J, T_{stg}	- 55 to 150	°C

THERMAL RESISTANCE RATINGS					
Parameter		**Symbol**	**Typical**	**Maximum**	**Unit**
Maximum Junction-to-Ambient[b, d]	≤ 5 s	R_{thJA}	90	115	°C/W
Maximum Junction-to-Foot (Drain)	Steady State	R_{thJF}	60	75	

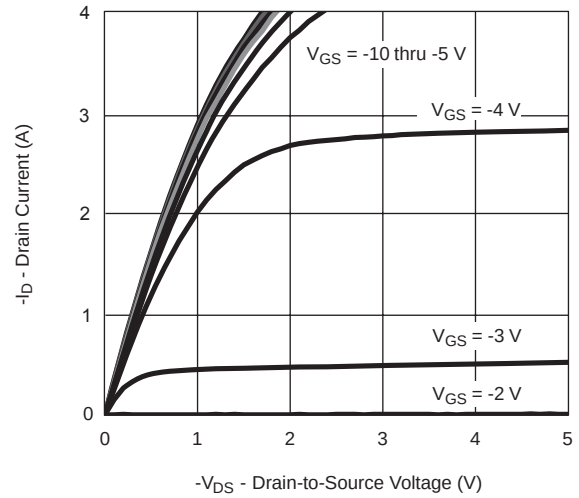
Notes:
a. Based on T_C = 25 °C.
b. Surface Mounted on 1" x 1" FR4 board.
c. t = 5 s.
d. Maximum under Steady State conditions is 120 °C/W.

MOSFET SPECIFICATIONS T_J = 25 °C, unless otherwise noted						
Parameter	**Symbol**	**Test Conditions**	**Min.**	**Typ.**	**Max.**	**Unit**
Static						
Drain-Source Breakdown Voltage	V_{DS}	V_{DS} = 0 V, I_D = -250 µA	-60			V
Gate-Source Threshold Voltage	$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = -250 µA	-1		-3	V
Gate-Source Leakage	I_{GSS}	V_{DS} = 0 V, V_{GS} = ± 20 V			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = -60 V, V_{GS} = 0 V			-1	µA
		V_{DS} = -60 V, V_{GS} = 0 V, T_J = 55 °C			-10	
On-State Drain Current[a]	$I_{D(on)}$	V_{DS} ≥ –5 V, V_{GS} = 10 V	-15			A
Drain-Source On-State Resistance[a]	$R_{DS(on)}$	V_{GS} = -10 V, I_D = -1.9 A		0.078	0.095	Ω
		V_{GS} = -4.5 V, I_D = -1.7 A		0.089	0.115	
Forward Transconductance[a]	g_{fs}	V_{DS} = -15V, I_D = -1.9 A		5		S
Dynamic[b]						
Input Capacitance	C_{iss}	V_{DS} = -30 V, V_{GS} = 0 V, f = 1 MHz		650		pF
Output Capacitance	C_{oss}			102		
Reverse Transfer Capacitance	C_{rss}			23		
Total Gate Charge	Q_g	V_{DS} = -30 V, V_{GS} = -10 V, I_D = -1.9 A		4.2		nC
		V_{DS} = -30 V, V_{GS} = -4.5 V, I_D = -1.7 A		2.1		
Gate-Source Charge	Q_{gs}			0.7		
Gate-Drain Charge	Q_{gd}			1		
Gate Resistance	R_g	f = 1 MHz		2.2		Ω
Turn-On Delay Time	$t_{d(on)}$	V_{DD} = -30 V, R_L = 20 Ω I_D ≅ -1.9 A, V_{GEN} = -10 V, R_G = 1 Ω		4		ns
Rise Time	t_r			10		
Turn-Off Delay Time	$t_{d(off)}$			10		
Fall Time	t_f			7		
Turn-On Delay Time	$t_{d(on)}$	V_{DD} = -30 V, R_L = 20 Ω I_D = -1.7 A, V_{GEN} = -4.5 V, R_G = 1 Ω		15		ns
Rise Time	t_r			16		
Turn-Off Delay Time	$t_{d(off)}$			11		
Fall Time	t_f			11		
Drain-Source Body Diode Characteristics						
Continuous Source-Drain Diode Current	I_S	T_C = 25 °C			-4	A
Pulse Diode Forward Current[a]	I_{SM}				-16	
Body Diode Voltage	V_{SD}	I_S = -1.5 A		-0.8	-1.2	V
Body Diode Reverse Recovery Time	t_{rr}	I_F = -1.5 A, dI/dt = 100 A/µs, T_J = 25 °C		15		ns
Body Diode Reverse Recovery Charge	Q_{rr}			10		nC
Reverse Recovery Fall Time	t_a			12		ns
Reverse Recovery Rise Time	t_b			3		

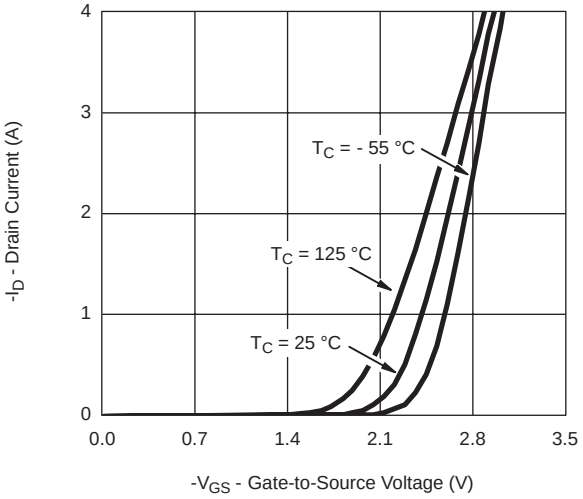
Notes:
a. Pulse test; pulse width ≤ 300 µs, duty cycle ≤ 2 %.
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

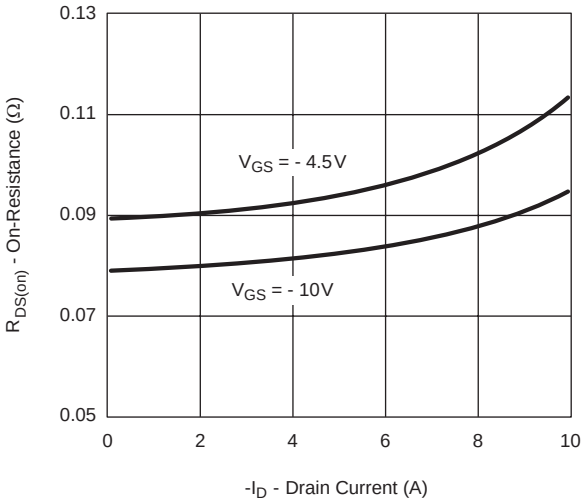
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



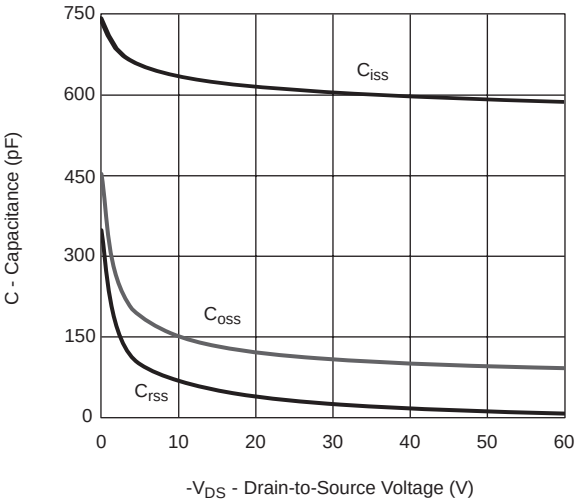
Output Characteristics



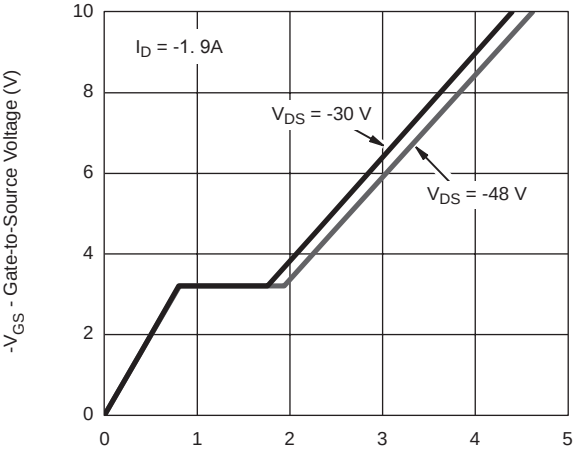
Transfer Characteristics



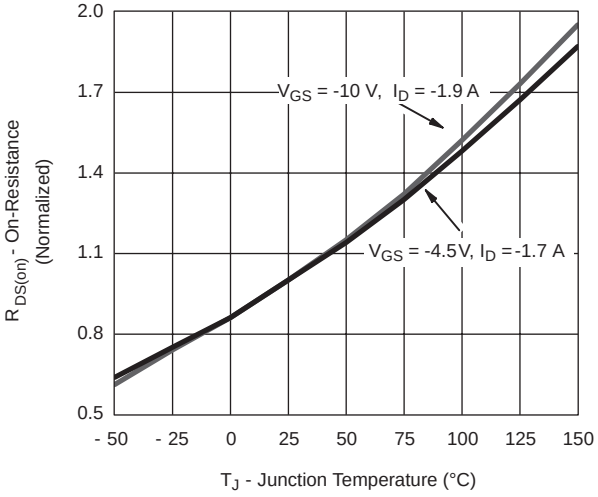
On-Resistance vs. Drain Current and Gate Voltage



Capacitance

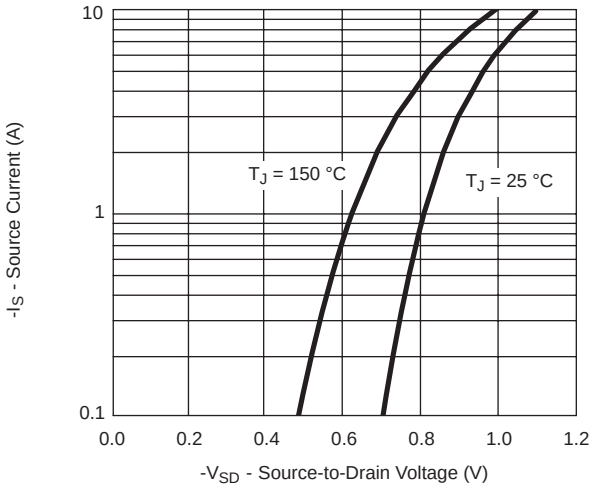


Gate Charge

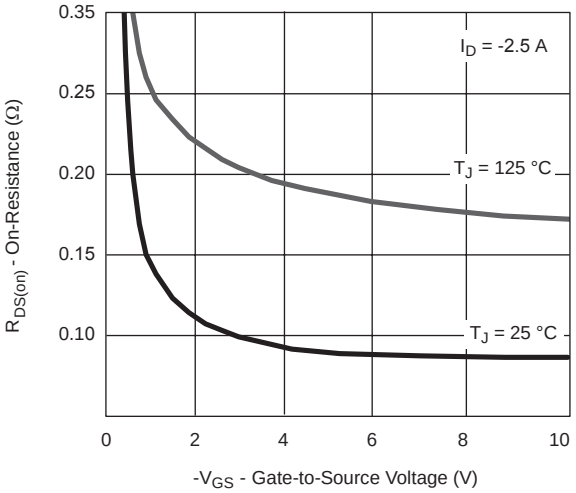


On-Resistance vs. Junction Temperature

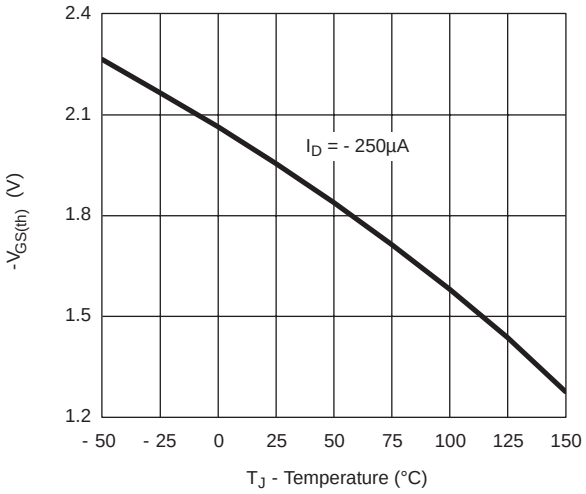
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



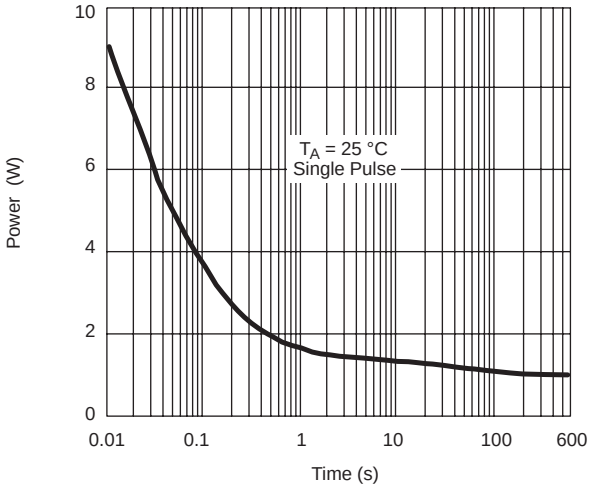
Source-Drain Diode Forward Voltage



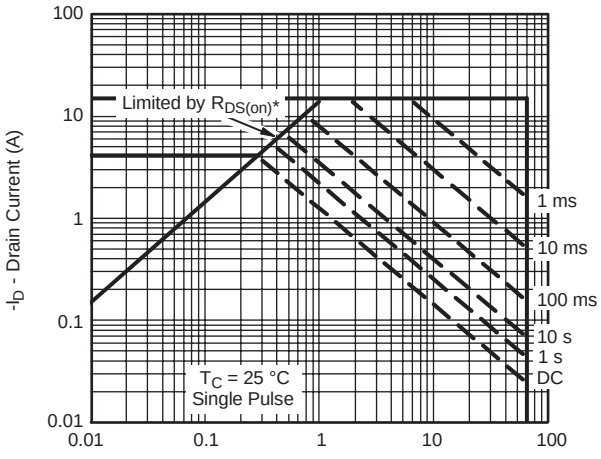
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



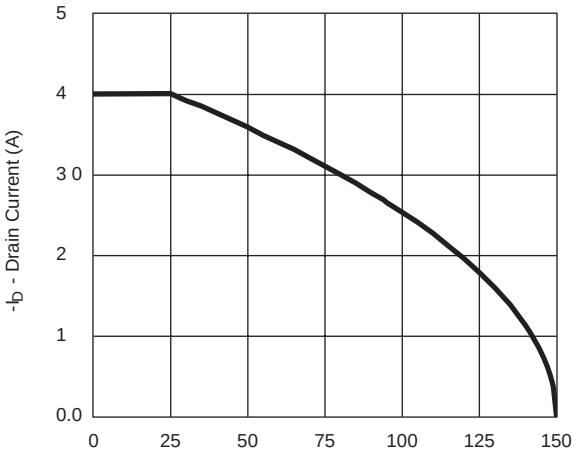
Single Pulse Power



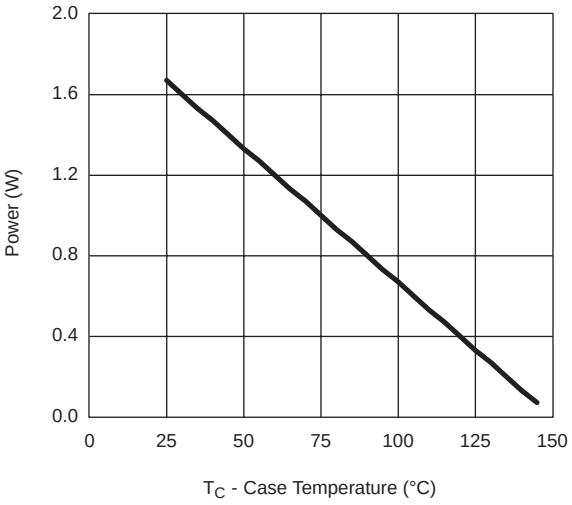
* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area, Junction-to-Ambient

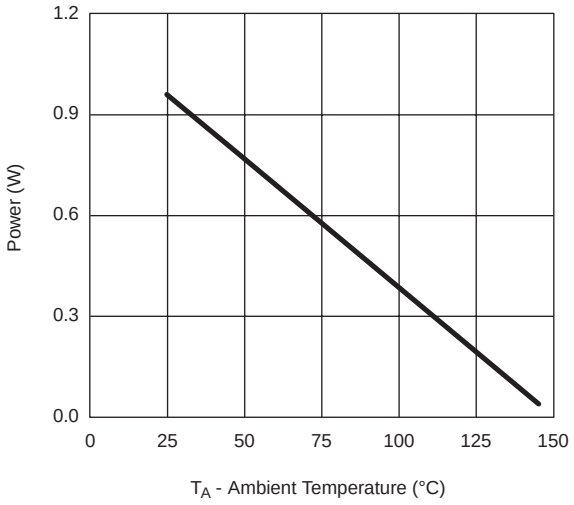
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Current Derating*



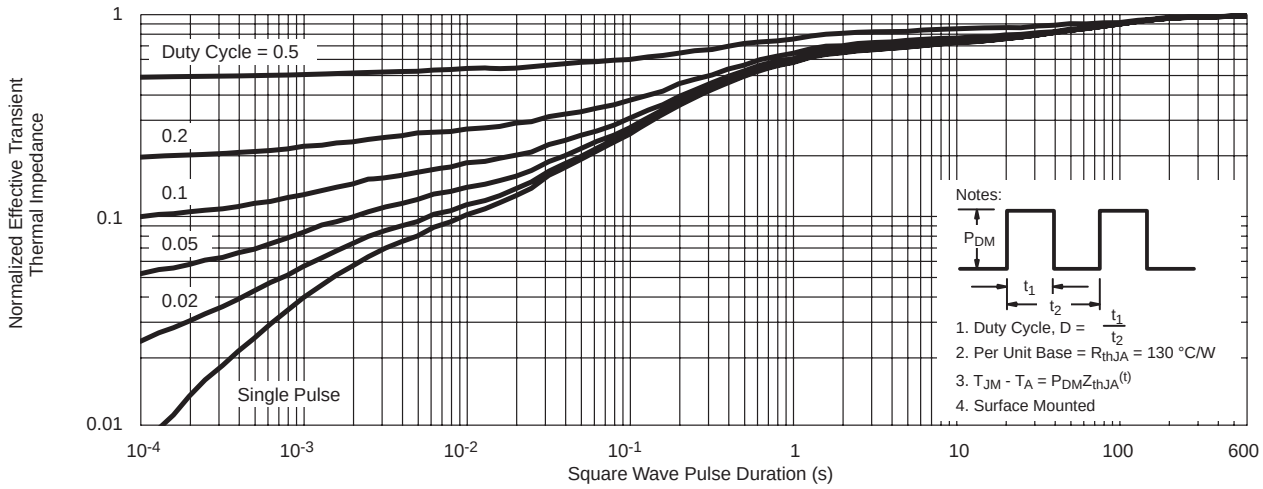
Power Derating, Junction-to-Case



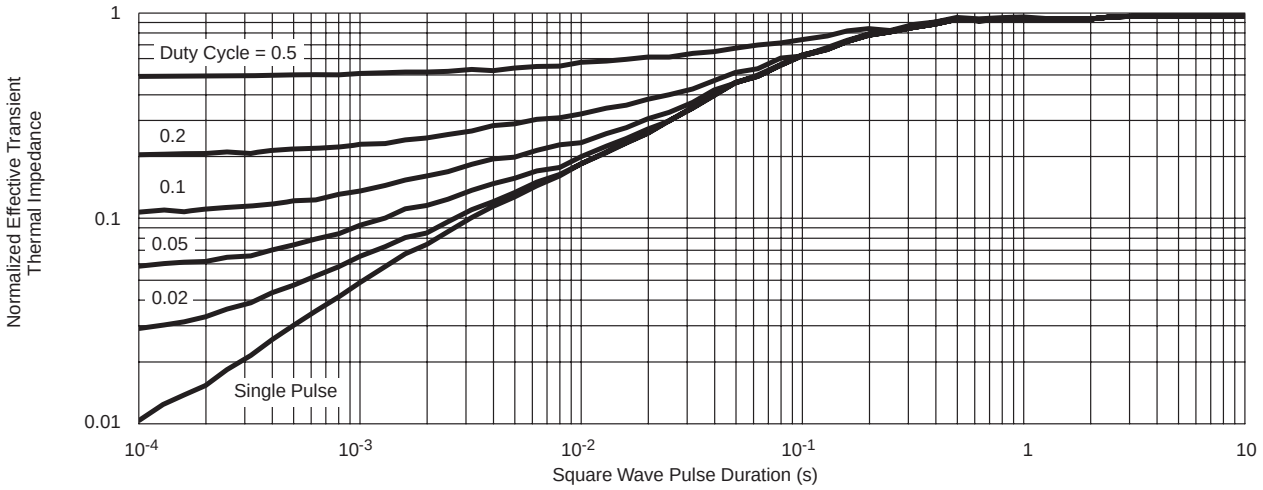
Power Derating, Junction-to-Ambient

* The power dissipation P_D is based on $T_{J(max.)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

THERMAL RATINGS (T_A = 25 °C, unless otherwise noted)

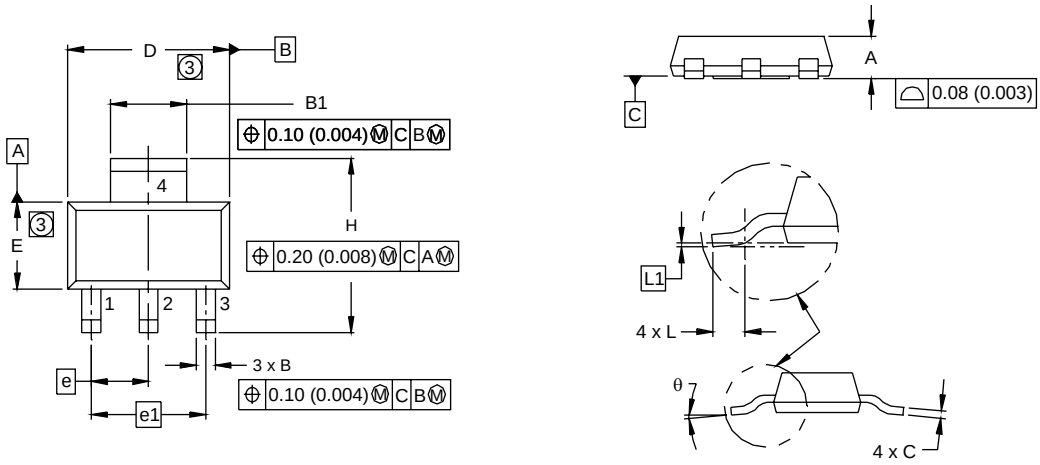


Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

SOT-223 (HIGH VOLTAGE)



	MILLIMETERS		INCHES	
DIM.	**MIN.**	**MAX.**	**MIN.**	**MAX.**
A	1.55	1.80	0.061	0.071
B	0.65	0.85	0.026	0.033
B1	2.95	3.15	0.116	0.124
C	0.25	0.35	0.010	0.014
D	6.30	6.70	0.248	0.264
E	3.30	3.70	0.130	0.146
e	2.30 BSC		0.0905 BSC	
e1	4.60 BSC		0.181 BSC	
H	6.71	7.29	0.264	0.287
L	0.91	-	0.036	-
L1	0.061 BSC		0.0024 BSC	
θ	-	10'	-	10'
ECN: S-82109-Rev. A, 15-Sep-08 DWG: 5969				

Notes

1. Dimensioning and tolerancing per ASME Y14.5M-1994.
2. Dimensions are shown in millimeters (inches).
3. Dimension do not include mold flash.
4. Outline conforms to JEDEC outline TO-261AA.

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